

METHOD OF FORMING HSQFN TYPE PACKAGE

Abstract of the Disclosure

5 A method of forming a HSQFN (High Stand-off Quad
Flat Non-leaded) package comprises providing a
leadframe with bonding pads and die pads for receiving
a die. Then, the die is attached on the die pad and
bonding wires are connected between the bonding pads
and the die for electrical connection. Molding
10 process is used to encompass the die by compound from
a first surface of the leadframe. Then, backside
etching is used to etch the leadframe from a second
surface of the leadframe to expose a lower surface of
the compound, thereby separating the bonding pads and
15 the die pads. A singulation is applied to separate each
individual package by cutting the leadframe and the
compound.

106040 50562800